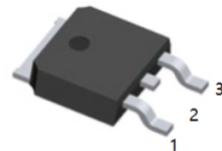


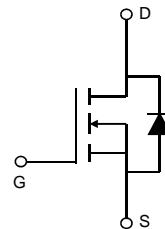
## General Description

- Latest Trench Power MOSFET technology
- Very Low  $R_{DS(on)}$  at 4.5V  $V_{GS}$
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

1.G 2.D 3.S  
TO-252(DPAK) top view

## Product Summary

- $V_{DS} = 30V$
- $I_D$  (at  $V_{GS} = 10V$ ) = 46A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) = < 5mΩ
- $R_{DS(ON)}$  (at  $V_{GS} = 4.5V$ ) = < 10mΩ



## Application

- DC/DC Converters in Computing
- Isolated DC/DC Converters in Telecom and Industrial

## Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>G</sup>	$I_D$	46	A
		36	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	170	
Continuous Drain Current	$I_{DSM}$	18	A
		14	
Avalanche Current <sup>C</sup>	$I_{AS}$	29	A
Avalanche energy $L=0.1mH$ <sup>C</sup>	$E_{AS}$	42	mJ
$V_{DS}$ Spike	100ns	$V_{SPIKE}$	V
Power Dissipation <sup>B</sup>	$P_D$	50	W
		25	
Power Dissipation <sup>A</sup>	$P_{DSM}$	2.5	W
		1.6	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	16	20	°C/W
Maximum Junction-to-Ambient <sup>AD</sup>		41	50	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	2.5	3	°C/W

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	$\mu\text{A}$
$I_{GSS}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.8	2.2	2.6	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$		4	5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=20\text{A}$		7.1	10	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=20\text{A}$		83		S
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.7	1	V
$I_S$	Maximum Body-Diode Continuous Current <sup>G</sup>				46	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		1333		pF
$C_{oss}$	Output Capacitance			512		pF
$C_{rss}$	Reverse Transfer Capacitance			42		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	0.8	1.7	2.6	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=20\text{A}$		18.3	33	nC
$Q_g(4.5\text{V})$	Total Gate Charge			8.5	17	nC
$Q_{gs}$	Gate Source Charge			4.8		nC
$Q_{gd}$	Gate Drain Charge			2.5		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=0.75\Omega, R_{GEN}=3\Omega$		7.5		ns
$t_r$	Turn-On Rise Time			4.8		ns
$t_{D(off)}$	Turn-Off Delay Time			23.3		ns
$t_f$	Turn-Off Fall Time			4.5		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$		14.1		ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$		16.2		nC

A. The value of  $R_{QJA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The Power dissipation  $P_{DSM}$  is based on  $R_{QJA}$  and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.

B. The power dissipation  $P_D$  is based on  $T_{J(MAX)}=175^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature  $T_{J(MAX)}=175^\circ\text{C}$ .

D. The  $R_{QJA}$  is the sum of the thermal impedance from junction to case  $R_{QJC}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)}=175^\circ\text{C}$ . The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

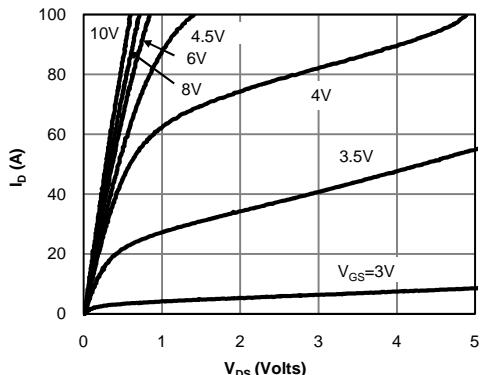


Fig 1: On-Region Characteristics (Note E)

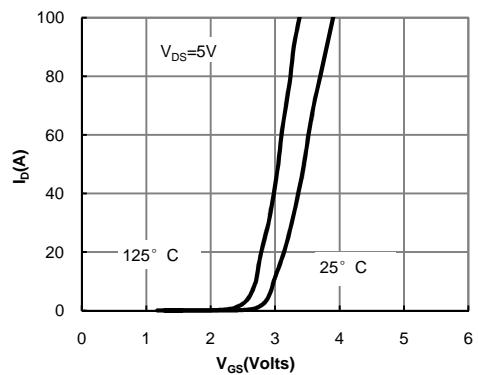


Figure 2: Transfer Characteristics (Note E)

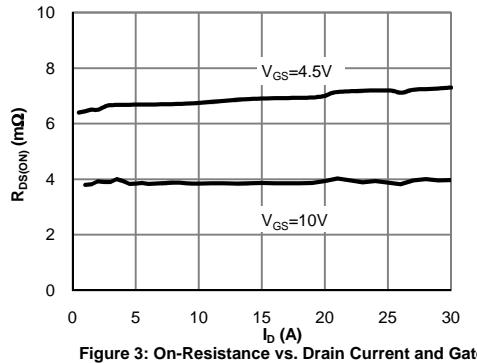


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

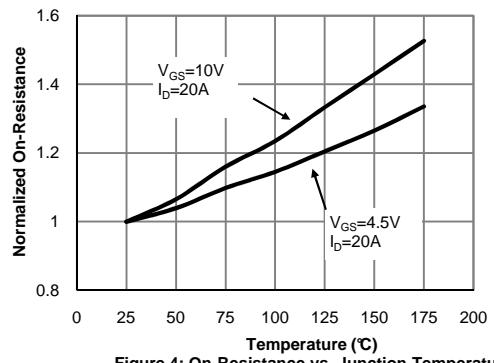


Figure 4: On-Resistance vs. Junction Temperature (Note E)

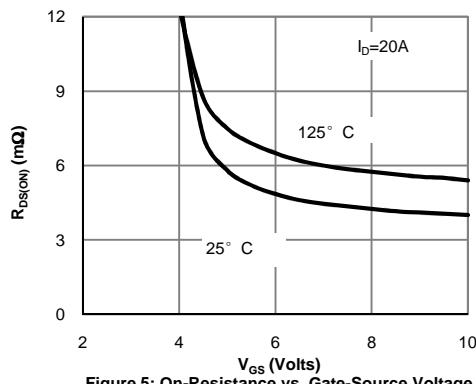


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

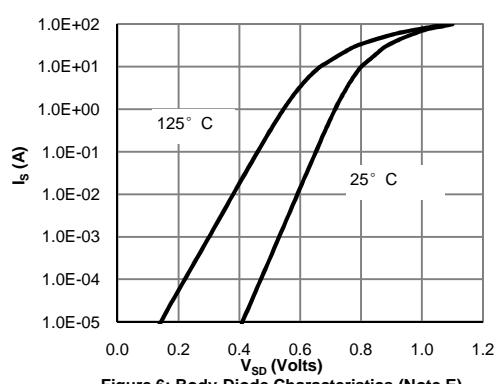


Figure 6: Body-Diode Characteristics (Note E)

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

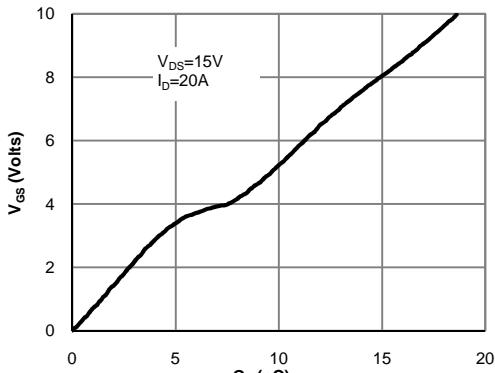


Figure 7: Gate-Charge Characteristics

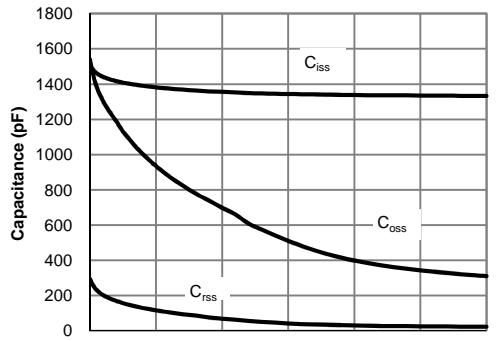


Figure 8: Capacitance Characteristics

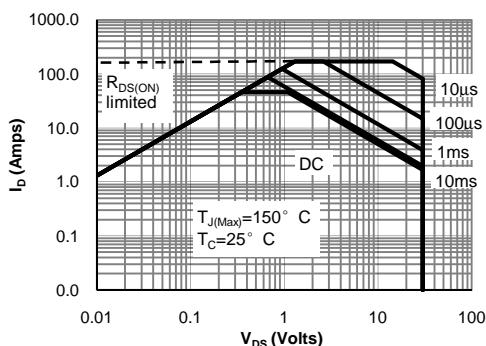


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

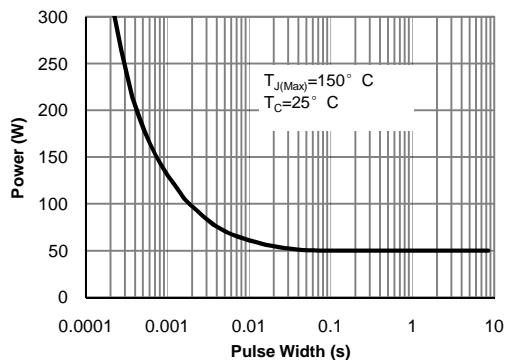


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

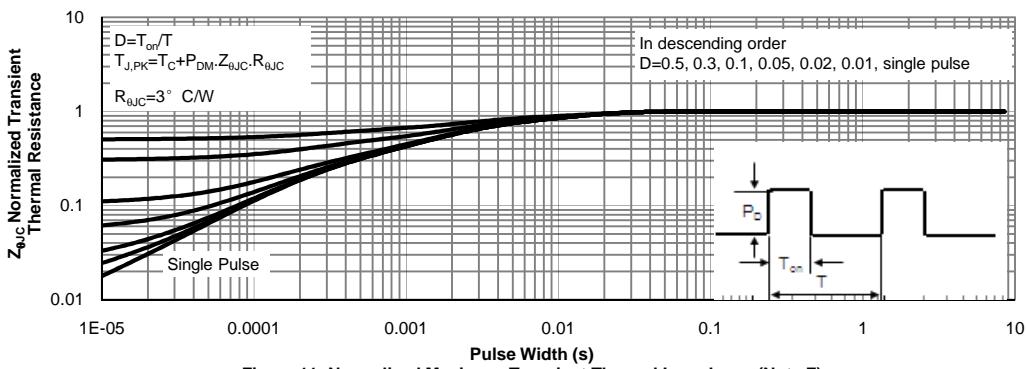


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

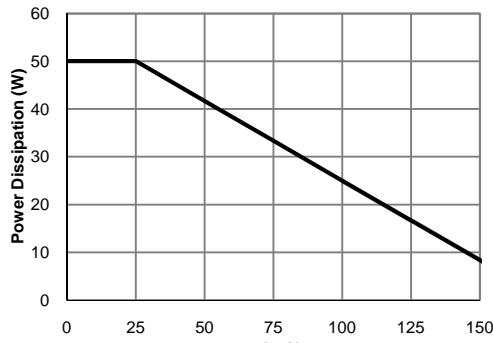


Figure 12: Power De-rating (Note F)

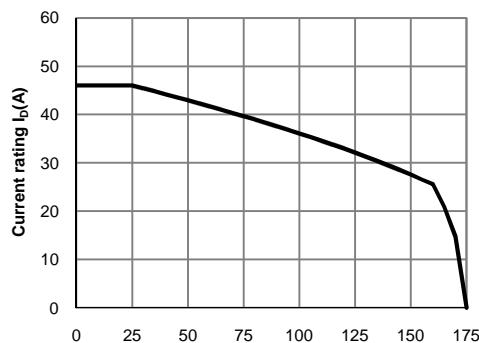


Figure 13: Current De-rating (Note F)

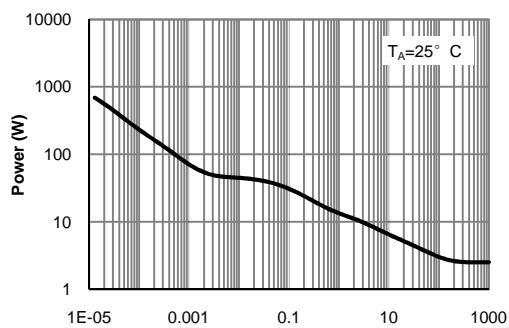


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

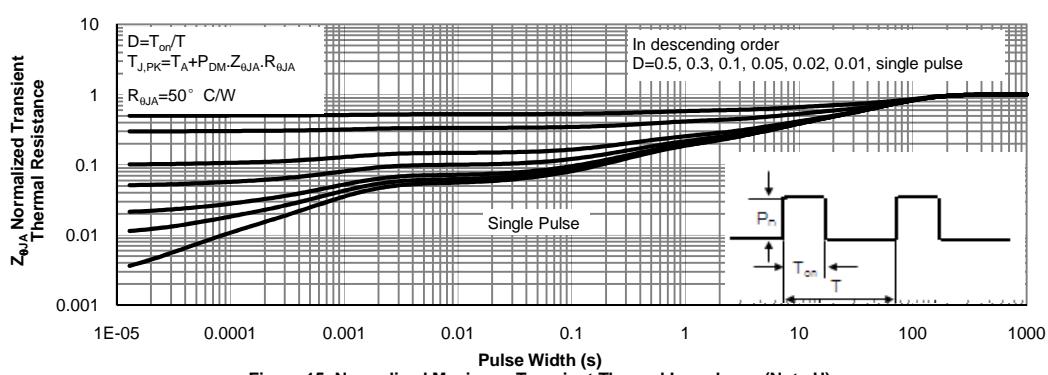
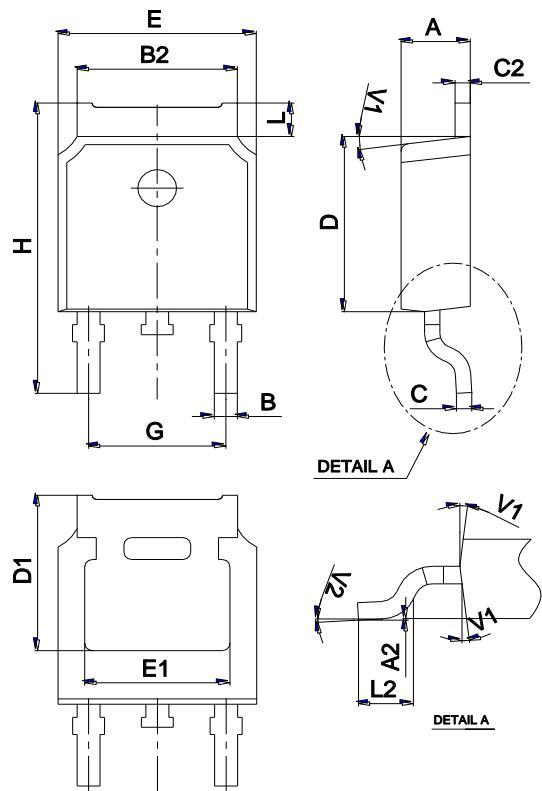


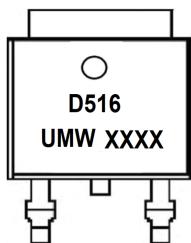
Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

## Package Mechanical Data TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## Marking



## Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AOD516	TO-252	2500	Tape and reel

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[MCQ7328-TP](#) [SSM3J143TU,LXHF](#) [DMN12M3UCA6-7](#) [PJMF280N65E1\\_T0\\_00201](#) [PJMF380N65E1\\_T0\\_00201](#)  
[PJMF280N60E1\\_T0\\_00201](#) [PJMF600N65E1\\_T0\\_00201](#) [PJMF900N65E1\\_T0\\_00201](#)